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GaAs MMIC I/Q DOWNCONVERTER 17 - 24 GHz

Typical Applications

The HMC904LC5 is ideal for:

- Point-to-Point and Point-to-Multi-Point Radio
- · Military Radar, EW & ELINT
- Satellite Communications

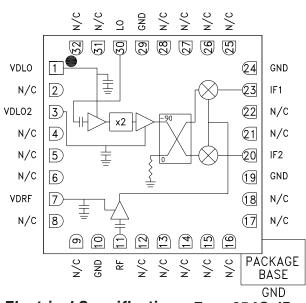
Features

Conversion Gain: 12 dB Image Rejection: 30 dB 2 LO to RF Isolation: 45 dB

Noise Figure: 3 dB Input IP3: 0 dBm

32 Lead 5x5mm SMT Package: 25mm²

Functional Diagram



General Description

The HMC904LC5 is a compact GaAs MMIC I/Q downconverter in a leadless RoHS compliant SMT package. This device provides a small signal conversion gain of 12 dB with a noise figure of 3 dB and 30 dB of image rejection across the frequency band. The HMC904LC5 utilizes an LNA followed by an image reject mixer which is driven by an active x2 multiplier. The image reject mixer eliminates the need for a filter following the LNA, and removes thermal noise at the image frequency. I and Q mixer outputs are provided and an external 90° hybrid is needed to select the required sideband. The HMC904LC5 is a much smaller alternative to hybrid style image reject mixer downconverter assemblies, and is compatible with surface mount manufacturing techniques.

Electrical Specifications, $T_A = +25$ °C, IF = 1000 MHz, LO = +4 dBm, Vdd = 3.5 Vdc USB [1]

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range, RF		17 - 20			20 - 24		GHz
Frequency Range, LO		7.5 - 11.75			8.25 - 12.3		GHz
Frequency Range, IF		DC - 3.5			DC - 3.5		GHz
Conversion Gain (As IRM)	8.5	12		8.5	12		dB
Noise Figure		3			3		dB
Image Rejection	20	35		15	30		dB
1 dB Compression (Input)		-8			-6		dBm
2 LO to RF Isolation	40	45		32	40		dB
2 LO to IF Isolation	10	15		15	20		dB
IP3 (Input)		0			0		dBm
Amplitude Balance [2]		0.25			0.25		dB
Phase Balance [2]		7			7		deg
Total Supply Current		160	190		160	190	mA

^[1] Data taken as IRM with external IF 90° Hybrid

^[2] Data taken without external 90° hybrid, IF = 500 MHz

HMC904* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

EVALUATION KITS

• HMC904LC5 Evaluation Board

DOCUMENTATION

Data Sheet

• HMC904 Data Sheet

REFERENCE MATERIALS -

Quality Documentation

- Package/Assembly Qualification Test Report: LC5, LC5A (QTR: 2014-00384 REV: 01)
- Semiconductor Qualification Test Report: PHEMT-A (QTR: 2013-00267)

DESIGN RESOURCES 🖵

- HMC904 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC904 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

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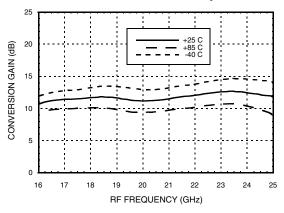




GaAs MMIC I/Q DOWNCONVERTER 17 - 24 GHz

Data Taken As IRM With External IF 90° Hybrid, IF = 1000 MHz

Conversion Gain USB vs. Temperature



Conversion Gain USB vs. LO Drive

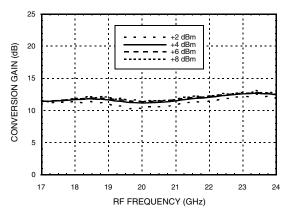
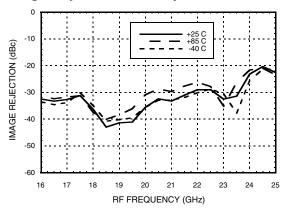
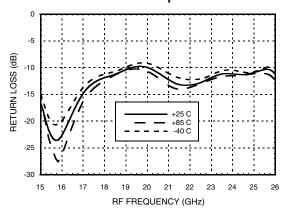


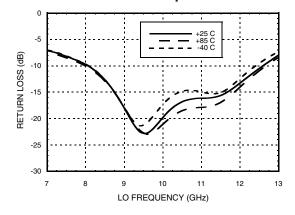
Image Rejection vs. Temperature



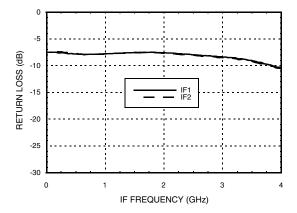
RF Return Loss vs. Temperature



LO Return Loss vs. Temperature



IF Return Loss [1]



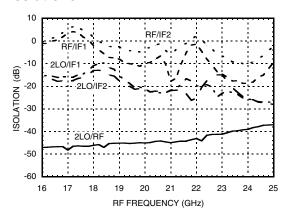
[1] Data taken without external 90° hybrid.



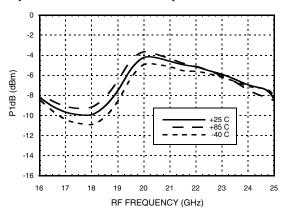


Data Taken as IRM With External IF 90° Hybrid, IF = 1000 MHz

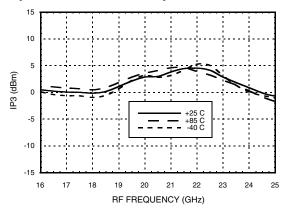
Isolations



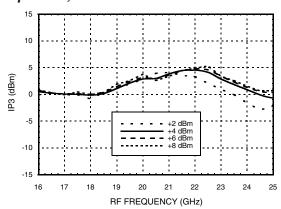
Input P1dB USB vs. Temperature



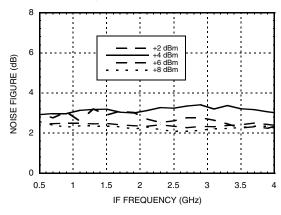
Input IP3, USB vs. Temperature



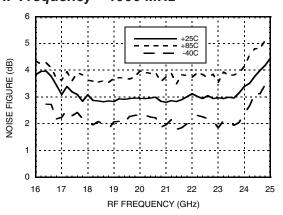
Input IP3, USB vs. LO Drive



Noise Figure vs. LO Drive, LO Frequency = 9 GHz



Noise Figure vs. Temperature, IF Frequency = 1000 MHz



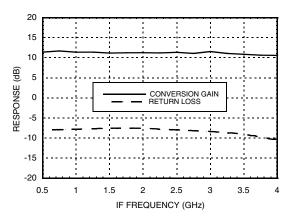
 $^{^{\}star}$ Conversion gain data taken with external IF 90° IF hybrid, LO frequency fixed at 8.5 GHz and RF varied



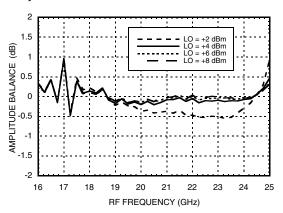


Quadrature Channel Data Taken Without IF 90° Hybrid, IF = 1000 MHz

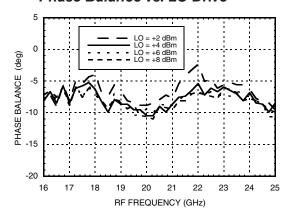
IF Bandwidth



Amplitude Balance vs. LO Drive [1]



Phase Balance vs. LO Drive [1]

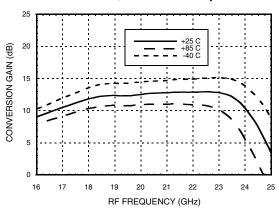






Data Taken as IRM With External IF 90° Hybrid, IF = 1000 MHz

Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

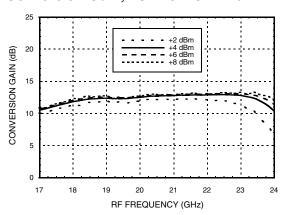
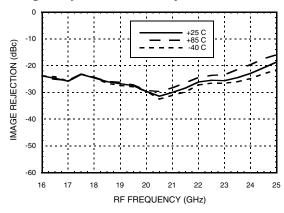
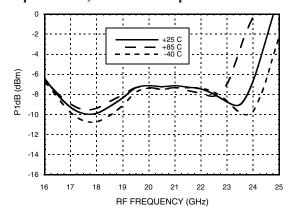


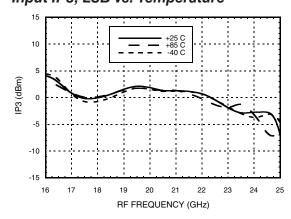
Image Rejection vs. Temperature



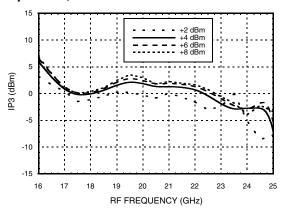
Input P1dB, LSB vs. Temperature



Input IP3, LSB vs. Temperature



Input IP3, LSB vs. LO Drive



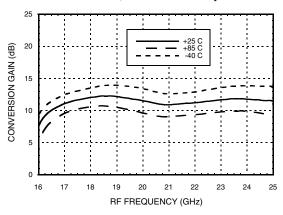
^{*} Conversion gain data taken with external IF 90° IF hybrid, LO frequency fixed at 8.5 GHz and RF varied





Data Taken as IRM With External IF 90° Hybrid, IF = 2000 MHz

Conversion Gain, USB vs. Temperature



Conversion Gain, USB vs. LO Drive

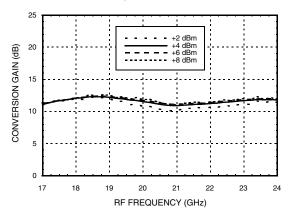
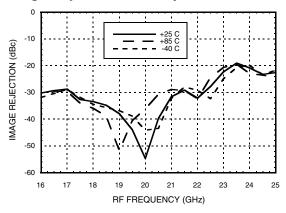
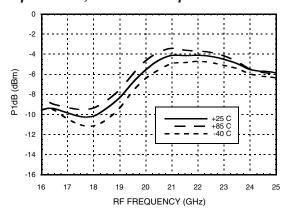


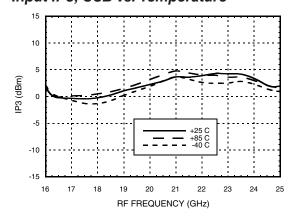
Image Rejection vs. Temperature



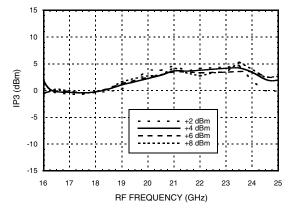
Input P1dB, USB vs. Temperature



Input IP3, USB vs. Temperature



Input IP3, USB vs. LO Drive



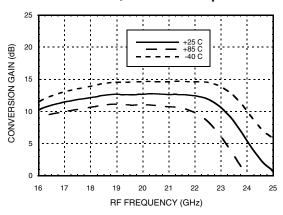
^{*} Conversion gain data taken with external IF 90° IF hybrid, LO frequency fixed at 8.5 GHz and RF varied





Data Taken as IRM With External IF 90° Hybrid, IF = 2000 MHz

Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

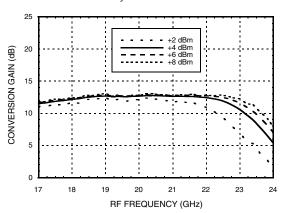
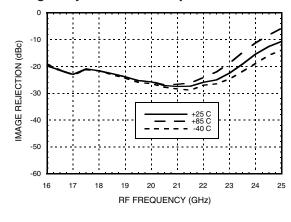
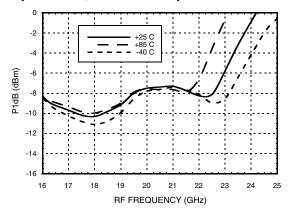


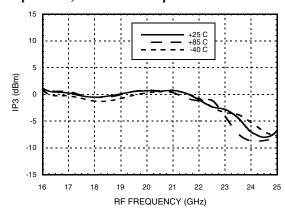
Image Rejection vs. Temperature



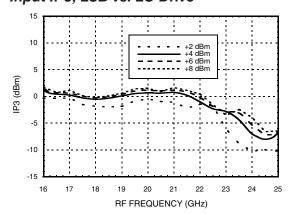
Input P1dB, LSB vs. Temperature



Input IP3, LSB vs. Temperature



Input IP3, LSB vs. LO Drive



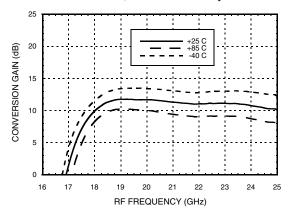




Data Taken as IRM With External IF 90° Hybrid, IF = 3350 MHz

v02.0511

Conversion Gain, USB vs. Temperature



Conversion Gain, USB vs. LO Drive

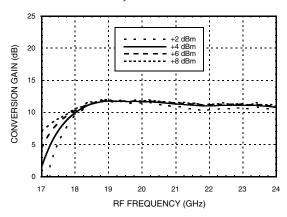
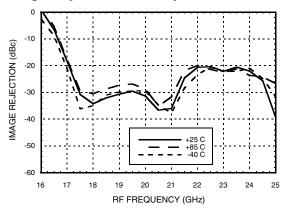
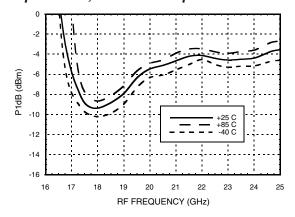


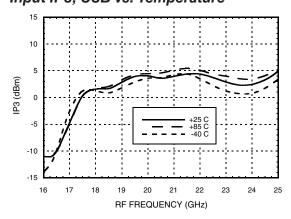
Image Rejection vs. Temperature



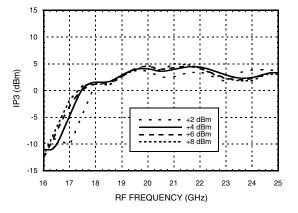
Input P1dB, USB vs. Temperature



Input IP3, USB vs. Temperature



Input IP3, USB vs. LO Drive



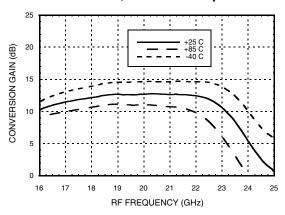
^{*} Conversion gain data taken with external IF 90° IF hybrid, LO frequency fixed at 8.5 GHz and RF varied





Data Taken as IRM With External IF 90° Hybrid, IF = 3350 MHz

Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

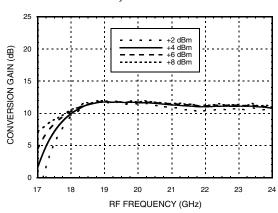
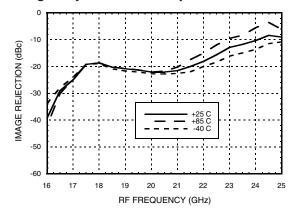
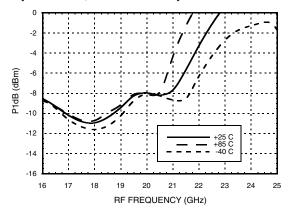


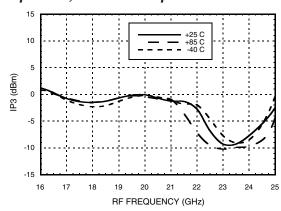
Image Rejection vs. Temperature



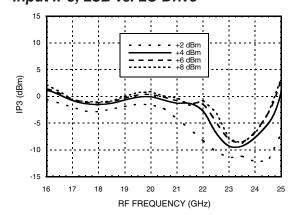
Input P1dB, LSB vs. Temperature



Input IP3, LSB vs. Temperature



Input IP3, LSB vs. LO Drive







GaAs MMIC I/Q DOWNCONVERTER 17 - 24 GHz

MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	-	17	0	23	33
1	8	26	0	23	24
2	68	95	0	66	48
3	xx	xx	xx	xx	xx
4	xx	XX	XX	xx	xx

RF = 18 GHz @ -20 dBm LO = 8.5 GHz @ +4 dBm Data taken without IF hybrid

All values in dBc below IF power level (1RF -2LO = 1 GHz)

Absolute Maximum Ratings

RF	+2 dBm
LO Drive	+10 dBm
Vdd	5.5V
Channel Temperature	175 °C
Continuous Pdiss (T=85°C) (derate 18.7 mW/°C above 85°C)	1.69 mW
Thermal Resistance (R _{TH}) (channel to package bottom)	53.2 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C
ESD Sensitivity (HBM)	Class 1B







Outline Drawing

BOTTOM VIEW 0.197±.005 PIN 32 .014 \[0.36 \] .009 \[0.24 \] .013 [0.32] [5.00±.13] 32 25 REF PIN 1 D 24 1 \Box 0.197±.005 [5.00±.13] H904 \Box \Box XXXX \Box \Box \Box 8 17 16 .138 [3.50] **EXPOSED SQUARE** LOT NUMBER **GROUND** 0.044 [1.12] .161 [4.10] **PADDLE** MAX **SEATING** PLANE NOTES: 1. PACKAGE BODY MATERIAL: ALUMINA -C-2. LEAD AND GROUND PADDLE PLATING: 30 - 80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKLE 3. DIMENSIONS ARE IN INCHES [MILLIMETERS]

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC904LC5	Alumina, White	Gold over Nickel	MSL3 ^[1]	H904 XXXX

^[1] Max peak reflow temperature of 260 °C

LEAD SPACING TOLERANCE IS NON-CUMULATIVE
 PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
 ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED

TO PCB RF GROUND

^{[2] 4-}Digit lot number XXXX



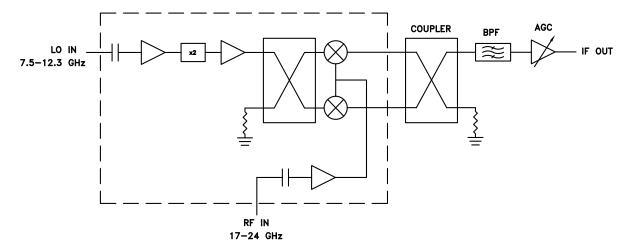


GaAs MMIC I/Q DOWNCONVERTER 17 - 24 GHz

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	VDLO	Power supply for first stage of LO amplifier.	VDLO ○
2, 4 - 6, 8, 9, 12 - 18, 21, 22, 25 - 28, 31, 32	N/C	The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
3	VDLO2	Power supply for second stage of LO amplifier.	VDLO2 ○ =
7	VDRF	Power supply for RF LNA.	
10, 19, 24, 29	GND	These pins and the exposed ground paddle must be connected to RF/DC ground.	○ GND —
11	RF	This pin is AC coupled and matched to 50 Ohms	RF ○— —
20	IF2	This pin is DC coupled. For applications not requiring operation to DC this port should be DC blocked externally using a series capacitor whose value has	IF1,IF2 O
23	IF1	been chosen to pass the necessary frequency range. For operation to DC, this pin must not sink / source more than 3 mA of current or part non-function and possible failure will result.	
30	LO	This pin is AC coupled and matched to 50 Ohms.	LO 0

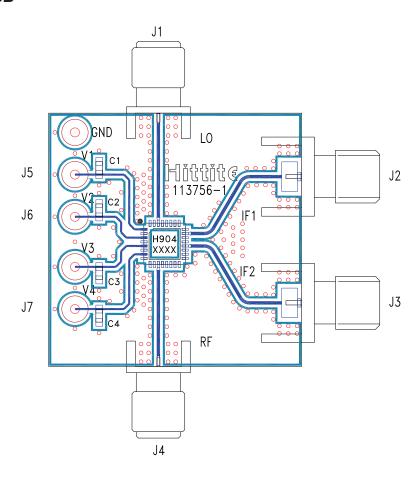
Typical Application Circuit







Evaluation PCB



List of Materials for Evaluation PCB 113758 [1]

Item	Description	
J1, J4	PCB Mount SMA RF Connector, SRI	
J2, J3	PCB Mount SMA Connector, Johnson	
J5 - J7	DC Pin	
C1 - C4	0.01 μF Capacitor, 0603 Pkg.	
U1	HMC904LC5	
PCB [2]	113756 Evaluation Board	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.







MIXERS - I/Q MIXERS, IRMS & RECEIVERS - SMT

